Abstracts

A Low-Inductance Millimeter-Wave Semiconductor Package (Correspondence)

R.R. Spiwak. "A Low-Inductance Millimeter-Wave Semiconductor Package (Correspondence)." 1971 Transactions on Microwave Theory and Techniques 19.8 (Aug. 1971 [T-MTT]): 732-733.

A low-inductance semiconductor device package has been fabricated for use in the microwave and millimeter-wave ranges where the parasitic resonances of conventional packages interfere with circuit design. This method of packaging eliminates the use of springs or ribbons normally used to contact the semiconductor and has resulted in a package in which the first self-resonance is calculated to be over 200 GHz. The package has been used successfully in several experimental applications over the past two years.

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